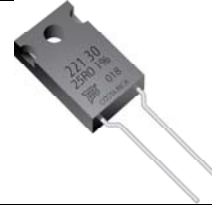


MATERIAL DECLARATION



Material Number	PWR221T-30-XXX		
Product Line	Power Resistor		
Compliance Date			
RoHS Compliant	yes	MSL	N/A



No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Housing	Epoxy Molding Compound	0.6443	Silica	14808-60-7	53	27.88	52.6
				Epoxy Resin	29690-82-2	25	13.15	
				Phenolic Resin	9003-35-4	15	7.89	
				Antimony trioxide	1309-64-4	3	1.58	
				Brominated epoxy resin	40039-93-8	3	1.58	
				Carbon Black	1333-86-4	1	0.58	
2	Terminal	Copper	0.2510	Copper	7440-50-8	99.95	20.48	20.49
				Other		0.05	0.01	
		Plating	0.016	Tin	7440-31-5	100	1.30	1.30
3	Substrate	Alumina	0.3089	Aluminum Oxide	1344-28-1	88	22.19	25.21
				Manganese dioxide	1313-13-9	3.5	0.88	
				Titanium-dioxide	13463-67-7	3.5	0.88	
				Chromium(III)oxide	1308-38-9	2.5	0.63	
				Quartz (Silicon dioxide)	14808-60-7	2.5	0.63	
4	Term Ink	Ink	0.0011	Silver	7440-22-4	96	0.09	0.09
				Lead-Oxide	1309-60-0	1	0.001	
				Dibismuth-trioxide	1304-76-3	1	0.001	
				Platinum	7440-06-4	1	0.001	
				Confidential Substances		1	0.001	

MATERIAL DECLARATION



5	Resistor Paste	Ink	0.0023	Palladium	7440-05-3	25	0.05	0.18
				Boraluminosilicate glass	65997-17-3	30	0.06	
				Trimethylpentanediol monoisobutyrate	25265-77-4	25	0.05	
				Silver	7440-22-4	15	0.03	
				Ruthenium dioxide	12036-10-1	1	0.002	
				Manganese dioxide	1313-13-9	1	0.002	
				Alumina	1344-28-1	3	0.006	
8	Encapsulant	Ink	0.0005	Lead-monoxide	1317-36-8	56.63	0.07	0.12
				Silicon dioxide	7631-86-9	27.89	0.03	
				Diboron-trioxide	1303-86-2	9.15	0.01	
				Chromium(III)oxide	1308-38-9	3.15	0.004	
				Confidential Substances		3.15	0.004	
Total weight			1.225					

This Document was updated on: June 22, 2010

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemptions: 5c – lead in glass of electronic components.